IN THE CLAIMS

Kindly amend claims 1, 3-9, 13-20, so that the claims appear as follows.

1. (Currently Amended) A method of making a water soluble protective paste for protecting metal circuits during the manufacture of electronic modules, comprising: mixing a salt, a glycerol and a densifier dissolved in water in a vacuum chamber, the salt being 5% to 110% of the glycerol by weight and the densifier being 5% to 90% of the salt by weight, at a temperature of at least 50°C.

2. (Previously Cancelled) The water soluble protective paste of claim 1 wherein the salt is 5% to 110% of the glycerol in weight and the densifier is 5% to 90% of the salt in weight.

3. (Currently Amended) The method ~~water soluble protective paste~~ of claim 2 wherein the salt is 8% to 30% of the glycerol in weight and the densifier is 7% to 25% of the salt in weight.

4. (Currently Amended) The method ~~water soluble protective paste~~ of claim 1 wherein the salt is Sodium citrate.

5. (Currently Amended) The method ~~water soluble protective paste~~ of claim 1, wherein the salt is Potassium citrate.

6. (Currently Amended) The method ~~water soluble protective paste~~ of claim 1 wherein the salt is about 25% of the glycerol in weight.

7. (Currently Amended) The method ~~water soluble protective paste~~ of claim 6 wherein the densifier is about 20% of the salt in weight.

8. (Currently Amended) The method ~~water-soluble protective paste~~ of claim 1 wherein the densifier is a Hydrocolloid.

9. (Currently Amended) The method ~~water-soluble protective paste~~ of claim 8 wherein the Hydrocolloid is Gum Acacia.

10. (Original) A method of selectively dispensing the water soluble protective paste of claim 1 by means of offset printing.

11. (Previously Presented) A method of protecting metal circuits and pads on the surface of an electronic board during manufacturing steps, comprising:

- selectively dispensing over the metal circuits and pads the water soluble protective paste of claim 1, by means of offset printing;
- drying the dispensed layer obtaining a solid protective film.

12. (Previously Presented) A method for manufacturing a multi chip module having on the same substrate at least one wire bonded chip and at least one Surface Mount Technology (SMT) chip, the method comprising the steps of:

- protecting, with the method of claim 11, the metal circuits and pads to which the wire bonded chip will be connected;
- mounting the at least one SMT chip;
- removing the protective layer from the metal circuits and pads;
- attaching and bonding the at least one wire bonded chip.

13. (Currently Amended) A method of making a water soluble protective paste for protecting metal circuits ~~during the manufacture of electronic modules~~, comprising: mixing a salt, a glycerol and a densifier dissolved in water in a vacuum chamber, the salt being about 25% of the glycerol by weight, at a temperature of not less than 50°C.

14. (Currently Amended) The method ~~water-soluble-protective-paste~~ of claim 13 wherein the salt is 5% to 110% of the glycerol in weight and the densifier is 5% to 90% of the salt in weight.

15. (Currently Amended) The method ~~water-soluble-protective-paste~~ of claim 14 wherein the salt is 8% to 30% of the glycerol in weight and the densifier is 7% to 25% of the salt in weight.

16. (Currently Amended) The method ~~water-soluble-protective-paste~~ of claim 13 wherein the salt is Sodium citrate.

17. (Currently Amended) The method ~~water-soluble-protective-paste~~ of claim 13, wherein the salt is Potassium citrate.

18. (Currently Amended) The method ~~water-soluble-protective-paste~~ of claim 13 wherein the densifier is about 20% of the salt in weight.

19. (Currently Amended) The method ~~water-soluble-protective-paste~~ of claim 13 wherein the densifier is a Hydrocolloid.

20. (Currently Amended) The method ~~water-soluble-protective-paste~~ of claim 19 wherein the Hydrocolloid is Gum Acacia.

21. (Previously Presented) A method of selectively dispensing the water soluble protective paste of claim 13 by means of offset printing.

22. (Currently Amended) A method of protecting metal circuits and pads on the surface of an electronic board ~~during manufacturing steps~~, comprising:

- selectively dispensing over the metal circuits and pads the water soluble protective paste of claim 13, by means of offset printing;

- drying the dispensed layer obtaining a solid protective film.

23. (Previously Presented) A method for manufacturing a multi chip module having on the same substrate at least one wire bonded chip and at least one Surface Mount Technology (SMT) chip, the method comprising the steps of:

- protecting, with the method of claim 22, the metal circuits and pads to which the wire bonded chip will be connected;
- mounting the at least one SMT chip;
- removing the protective layer from the metal circuits and pads;
- attaching and bonding the at least one wire bonded chip.